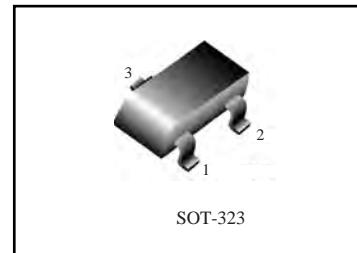


# Small Signal MOSFET

## 320 mAmps, 60 Volts

### N-Channel SOT-323

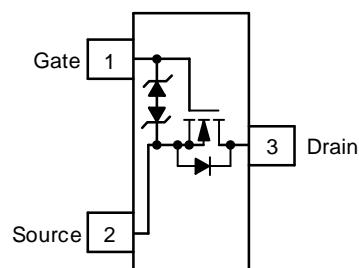
- We declare that the material of product are Halogen Free and compliance with RoHS requirements.
- ESD Protected:1000V
- AEC- Q101 qualified



#### MAXIMUM RATINGS(T<sub>a</sub> = 25 °C)

Rating	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	60	Vdc
Drain-Gate Voltage (R <sub>DS</sub> = 1.0 MΩ)	V <sub>DGR</sub>	60	Vdc
Drain Current			mAdc
– Continuous T <sub>C</sub> = 25 °C (Note 1.)	I <sub>D</sub>	±320	
T <sub>C</sub> = 100 °C (Note 1.)	I <sub>D</sub>	±75	
– Pulsed (Note 2.)	I <sub>DM</sub>	±800	
Gate-Source Voltage	V <sub>GS</sub>	±20	Vdc
– Continuous	V <sub>GSM</sub>	±40	Vpk

#### Simplified Schematic



(Top View)

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 3.) TA = 25 °C	P <sub>D</sub>	225	mW
Derate above 25		1.8	mW/°C
Thermal Resistance, Junction to Ambient	R <sub>θJA</sub>	556	°C/W
Total Device Dissipation Alumina Substrate,(Note 4.) T <sub>A</sub> = 25 °C	P <sub>D</sub>	300	mW
Derate above 25 °C		2.4	mW/°C
Thermal Resistance, Junction to Ambient	R <sub>θJA</sub>	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

1. The Power Dissipation of the package may result in a lower continuous drain current.

2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

3. FR-5 = 1.0 x 0.75 x 0.062 in.

4. Alumina = 0.4 x 0.3 x 0.025 in 99.5% alumina.

#### ORDERING INFORMATION

Device	Marking	Shipping
FTK7002U	6C	3000 Tape & Reel



# FTK7002U

**ELECTRICAL CHARACTERISTICS** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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## OFF CHARACTERISTICS

Drain–Source Breakdown Voltage ( $V_{GS} = 0$ , $I_D = 10 \mu\text{A}$ )	$V_{(\text{BR})\text{DSS}}$	60	–	–	Vdc
Zero Gate Voltage Drain Current ( $V_{GS} = 0$ , $V_{DS} = 60$ Vdc)	$I_{DSS}$	–	–	1.0 500	$\mu\text{A}$
Gate–Body Leakage Current, Forward ( $V_{GS} = 20$ Vdc)	$I_{GSSF}$	–	–	1	$\mu\text{A}$
Gate–Body Leakage Current, Reverse ( $V_{GS} = -20$ Vdc)	$I_{GSSR}$	–	–	-1	$\mu\text{A}$

## ON CHARACTERISTICS (Note 2.)

Gate Threshold Voltage ( $V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$ )	$V_{GS(\text{th})}$	1.0	1.6	2	Vdc
On–State Drain Current ( $V_{DS} \geq 2.0$ V <sub>DS(on)</sub> , $V_{GS} = 10$ Vdc)	$I_{D(\text{on})}$	500	–	–	mA
Static Drain–Source On–State Voltage ( $V_{GS} = 10$ Vdc, $I_D = 500$ mA)	$V_{DS(\text{on})}$	–	–	3.75	Vdc
( $V_{GS} = 5.0$ Vdc, $I_D = 50$ mA)		–	–	0.375	
Static Drain–Source On–State Resistance ( $V_{GS} = 10$ V, $I_D = 500$ mA) $T_C = 25^\circ\text{C}$ $T_C = 125^\circ\text{C}$ ( $V_{GS} = 5.0$ Vdc, $I_D = 50$ mA) $T_C = 25^\circ\text{C}$ $T_C = 125^\circ\text{C}$	$r_{DS(\text{on})}$	– – – –	1.4 – 1.8 –	7.5 13.5 7.5 13.5	Ohms
Forward Transconductance ( $V_{DS} \geq 2.0$ V <sub>DS(on)</sub> , $I_D = 200$ mA)	$g_{FS}$	80	–	–	mmhos

## DYNAMIC CHARACTERISTICS

Input Capacitance ( $V_{DS} = 25$ Vdc, $V_{GS} = 0$ , $f = 1.0$ MHz)	$C_{iss}$	–	17	50	pF
Output Capacitance ( $V_{DS} = 25$ Vdc, $V_{GS} = 0$ , $f = 1.0$ MHz)	$C_{oss}$	–	10	25	pF
Reverse Transfer Capacitance ( $V_{DS} = 25$ Vdc, $V_{GS} = 0$ , $f = 1.0$ MHz)	$C_{rss}$	–	2.5	5.0	pF

## SWITCHING CHARACTERISTICS (Note 2.)

Turn–On Delay Time	$(V_{DD} = 25$ Vdc, $I_D \cong 500$ mA), $R_G = 25 \Omega$ , $R_L = 50 \Omega$ , $V_{gen} = 10$ V)	$t_{d(\text{on})}$	–	7	20	ns
Turn–Off Delay Time		$t_{d(\text{off})}$	–	11	40	ns

## BODY–DRAIN DIODE RATINGS

Diode Forward On–Voltage ( $I_S = 115$ mA), $V_{GS} = 0$ V)	$V_{SD}$	–	–	-1.5	Vdc
Source Current Continuous (Body Diode)	$I_S$	–	–	-115	mA
Source Current Pulsed	$I_{SM}$	–	–	-800	mA

2. Pulse Test: Pulse Width  $\leq 300 \mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

## ELECTRICAL CHARACTERISTIC CURVES

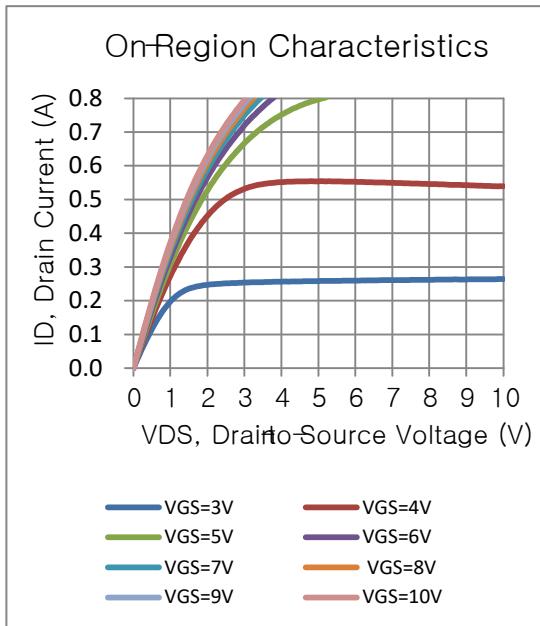


FIG1

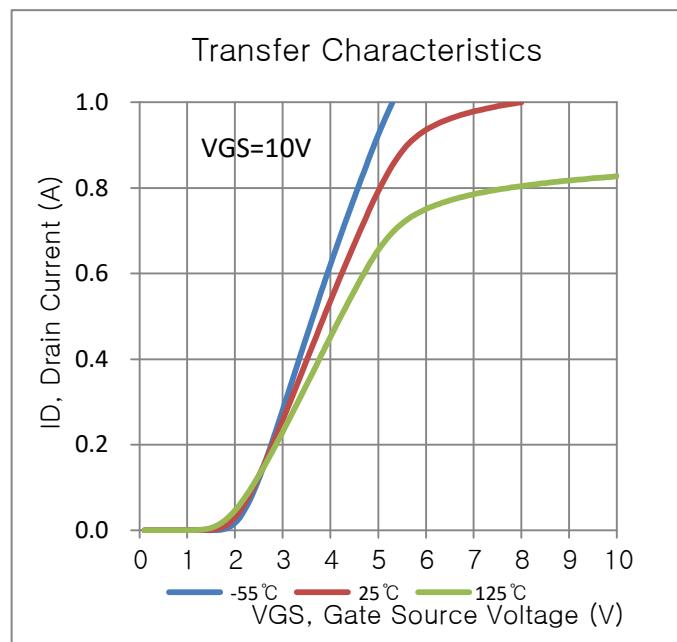


FIG2

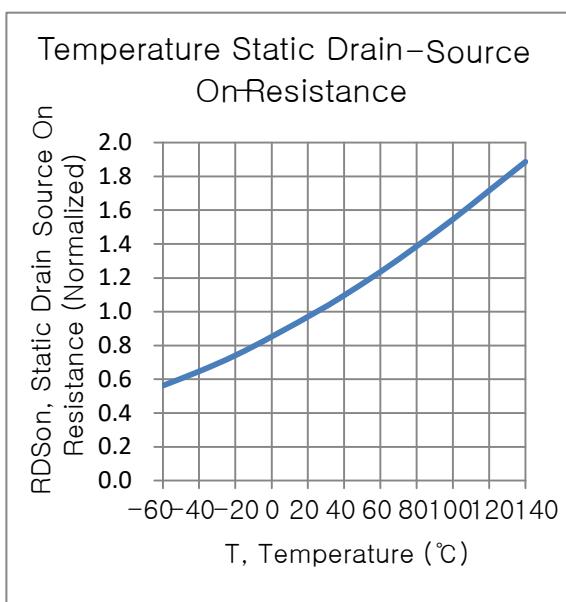


FIG3

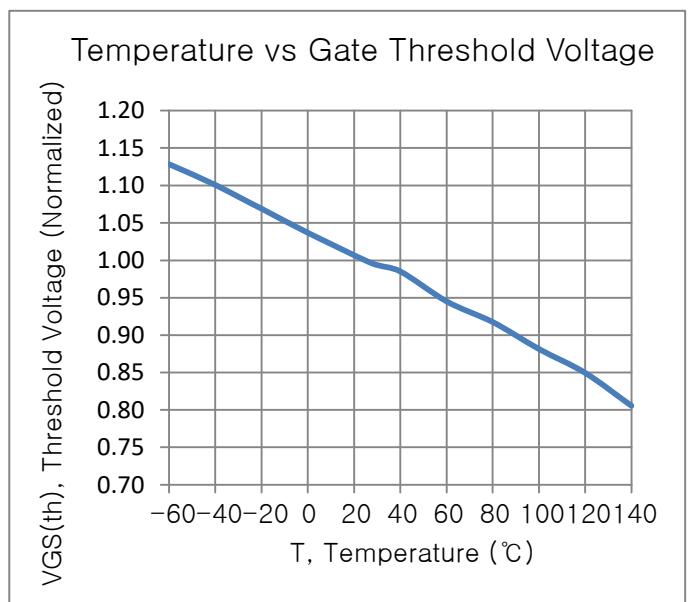
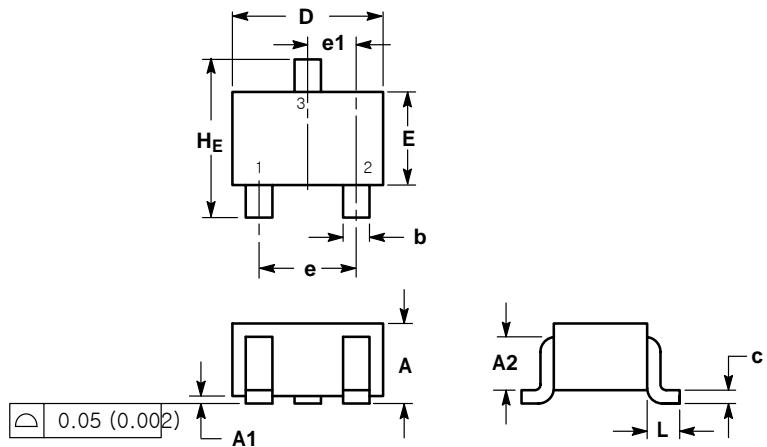


FIG4

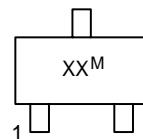
## SOT-323



NOTES:  
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.  
 2. CONTROLLING DIMENSION: INCH.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.032	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
A2	0.7 REF			0.028 REF		
b	0.30	0.35	0.40	0.012	0.014	0.016
c	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.10	2.20	0.071	0.083	0.087
E	1.15	1.24	1.35	0.045	0.049	0.053
e	1.20	1.30	1.40	0.047	0.051	0.055
e1	0.65 BSC			0.026 BSC		
L	0.425 REF			0.017 REF		
H_E	2.00	2.10	2.40	0.079	0.083	0.095

### GENERIC MARKING DIAGRAM



XX = Specific Device Code  
 M = Date Code  
 ■ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot, may or may not be present.

